

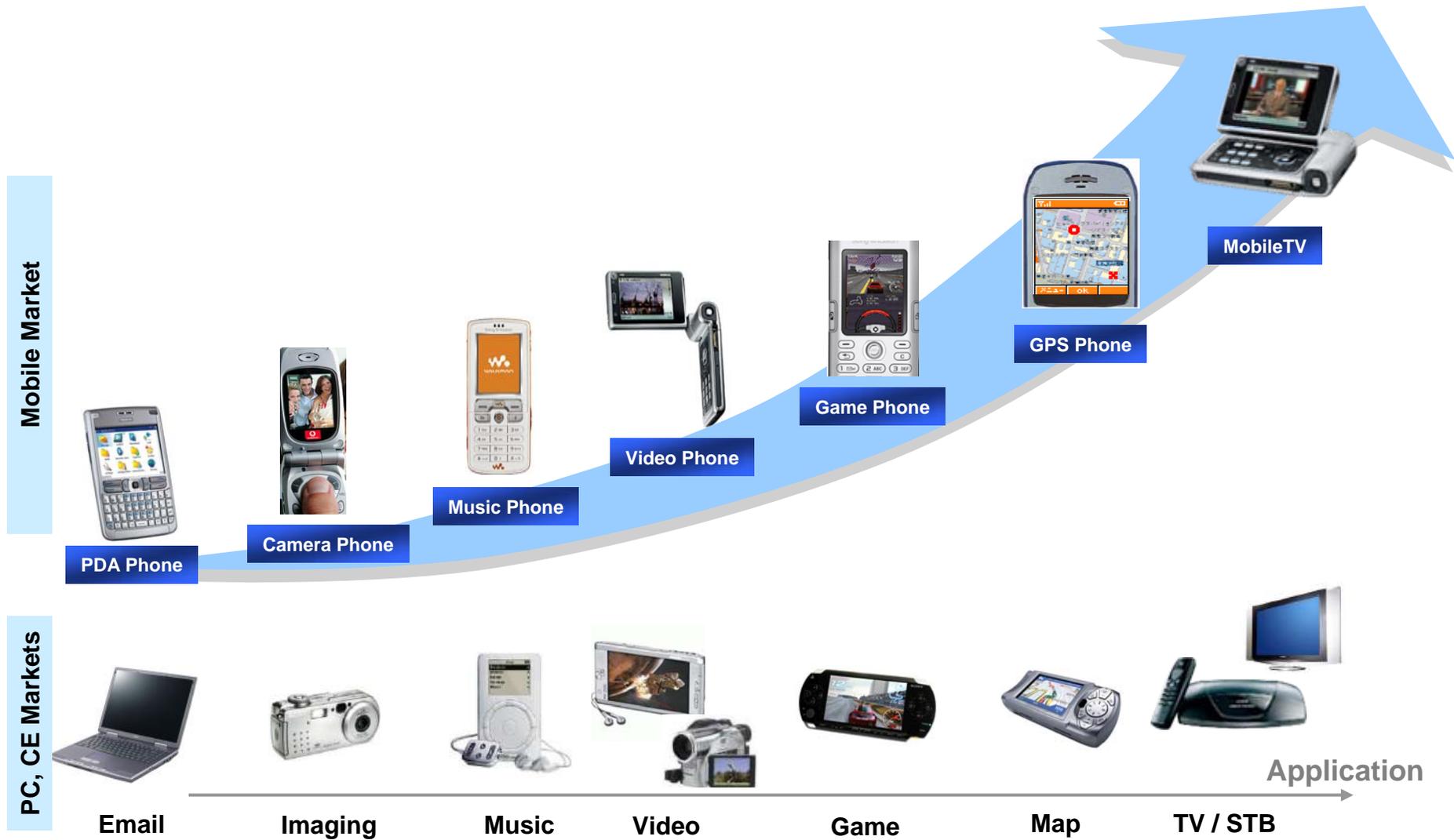
Nonvolatile Erasable Flash NAND Memories

Raul Adrian Cernea
SanDisk Corporation, Milpitas, California

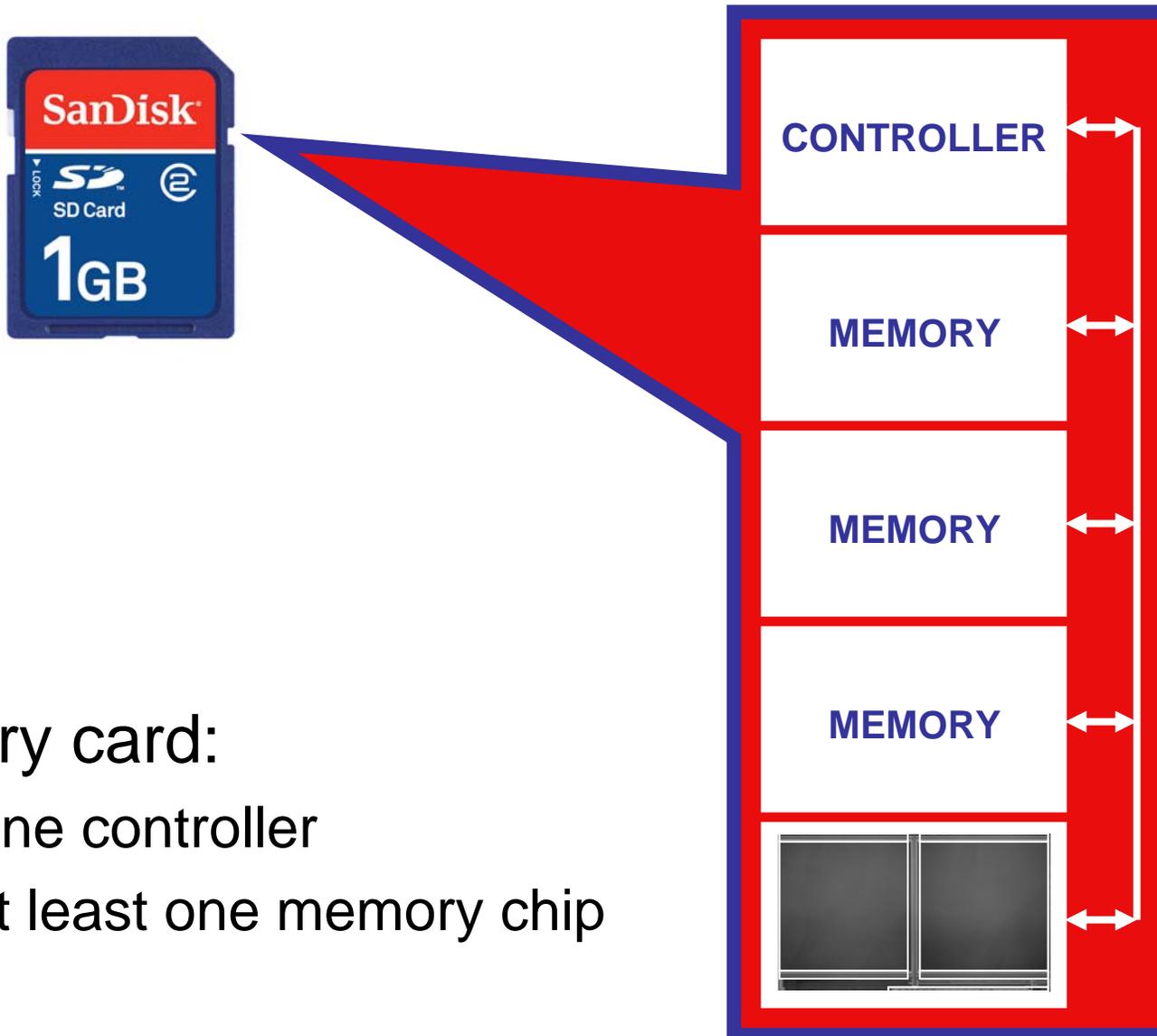
Outline

- NAND Flash and memory cards
- Basic operations and multi-level
- Performance trends and ABL
- 3X MLC program-throughput
- Die size challenge and solutions
- Accelerated data access rate
- 3 bits per cell
- Power and energy reduction
- Summary and conclusions

Mobile/CE/PC Driving NAND Future



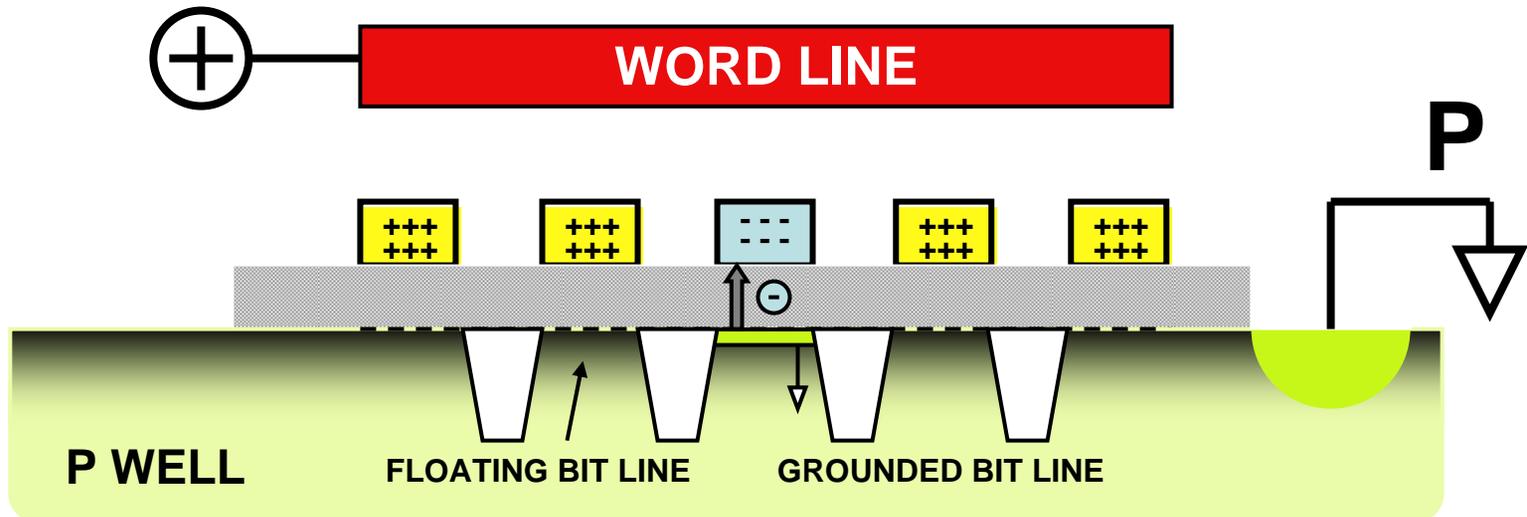
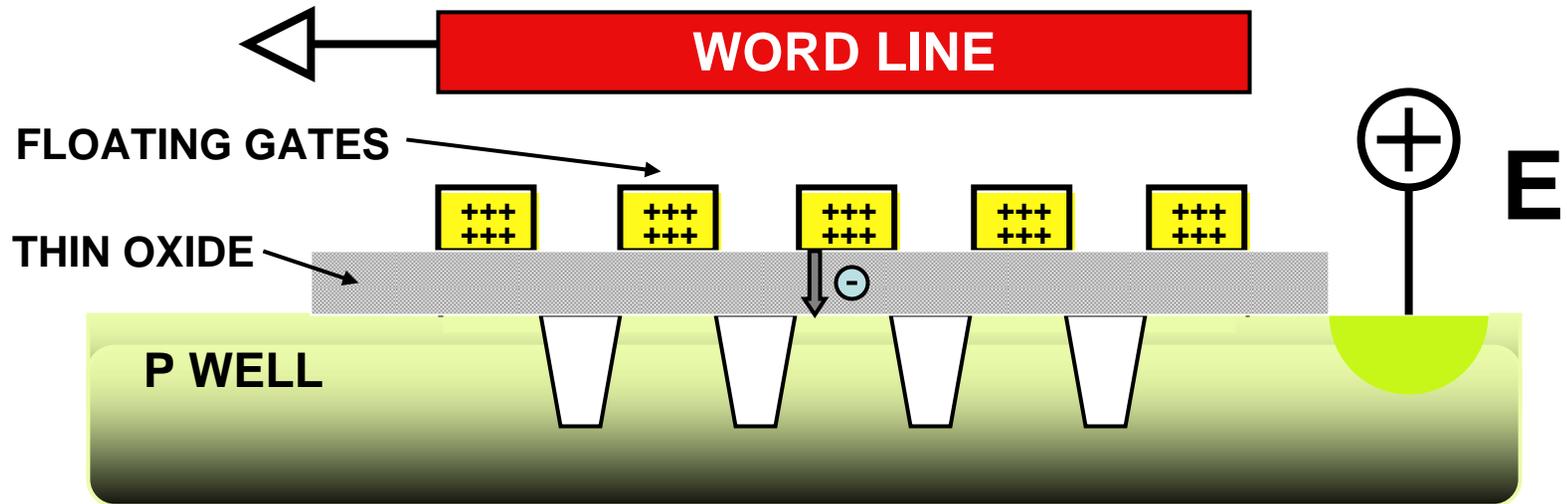
Memory cards



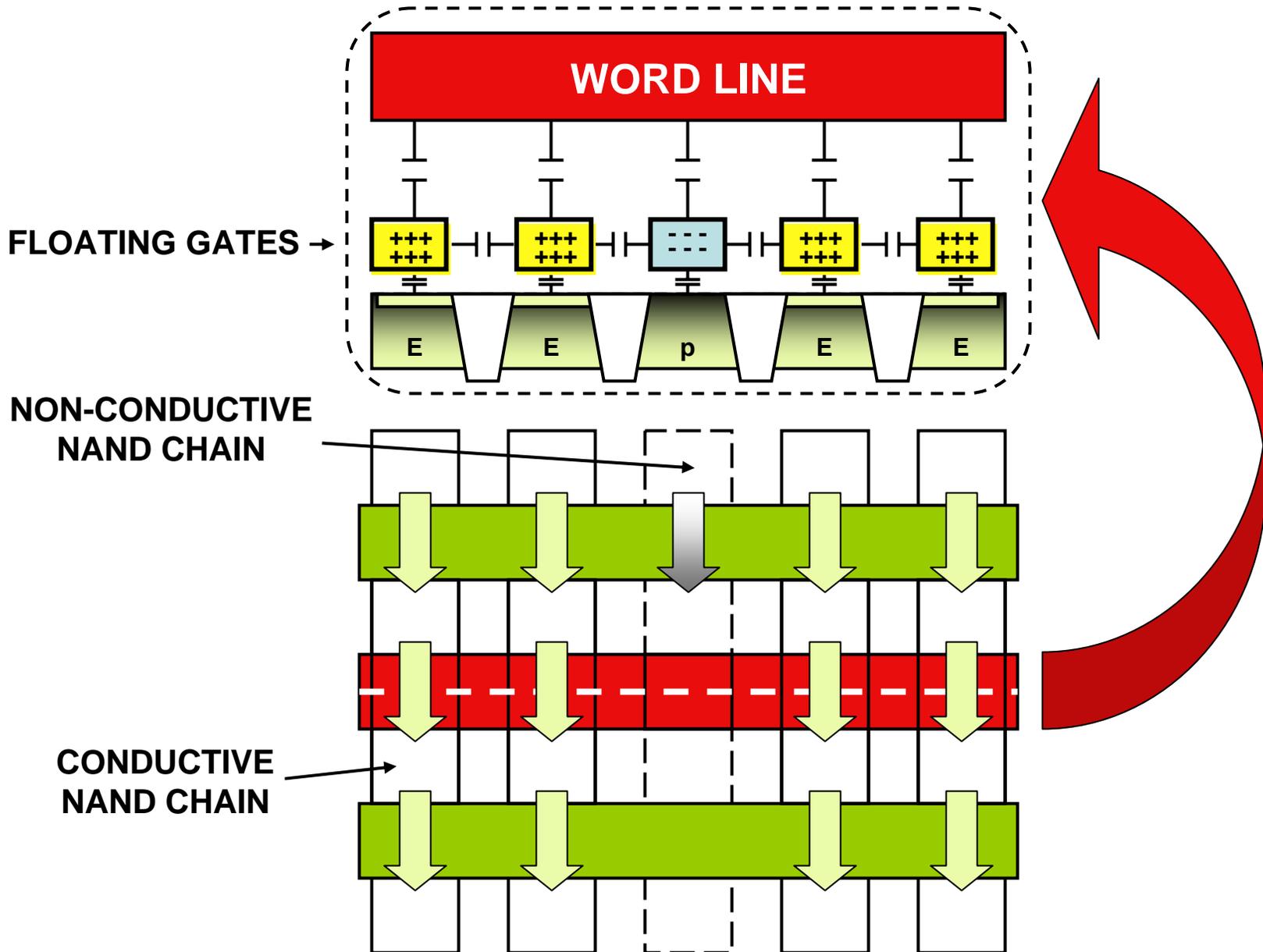
Every card:

- ➔ One controller
- ➔ At least one memory chip

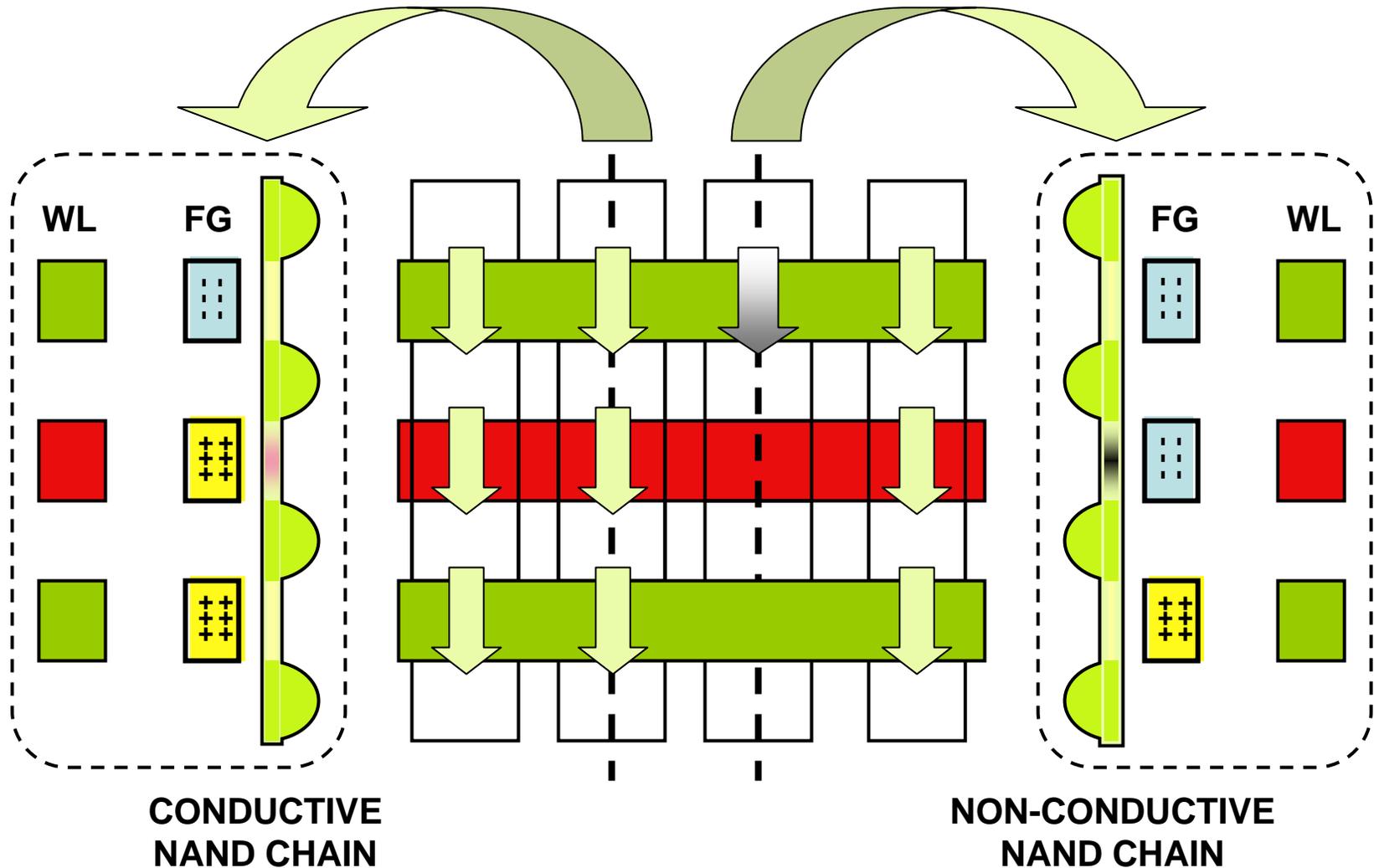
Erase and program



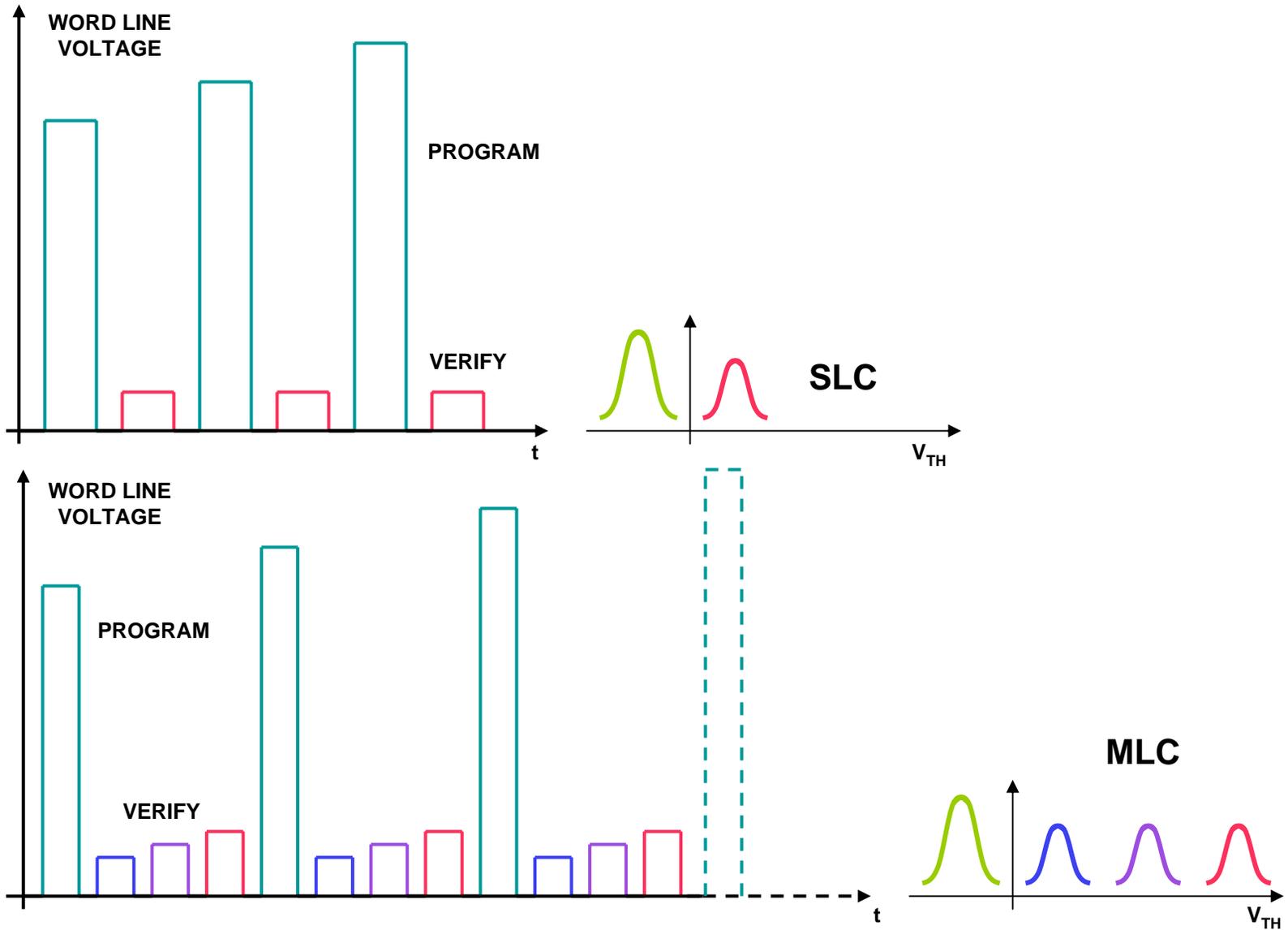
Cross-section along the Word Line



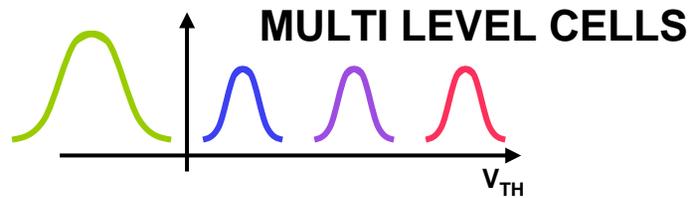
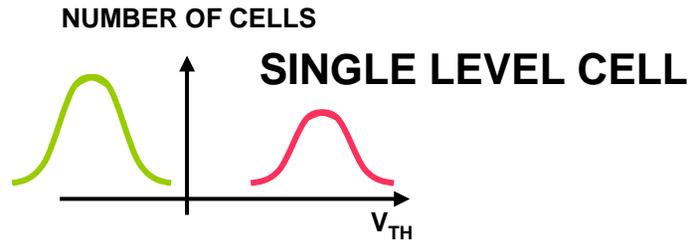
Cross-section along the Bit Line



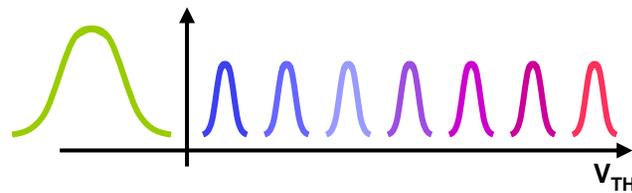
Program and verify



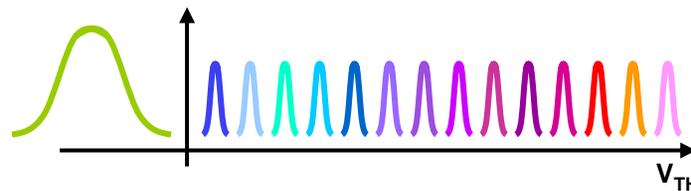
SLC and MLC



TWO BITS PER CELL



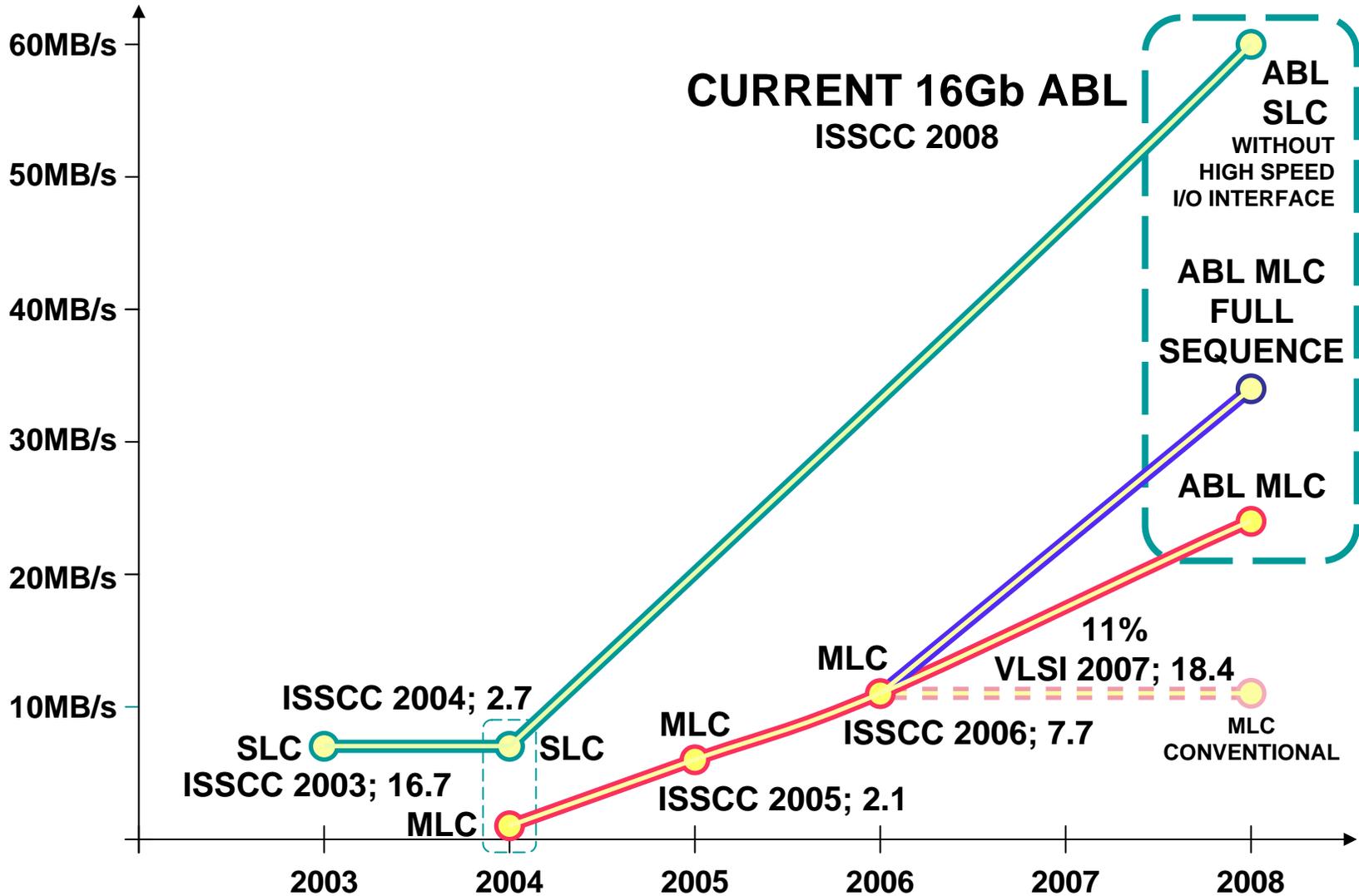
THREE BITS PER CELL



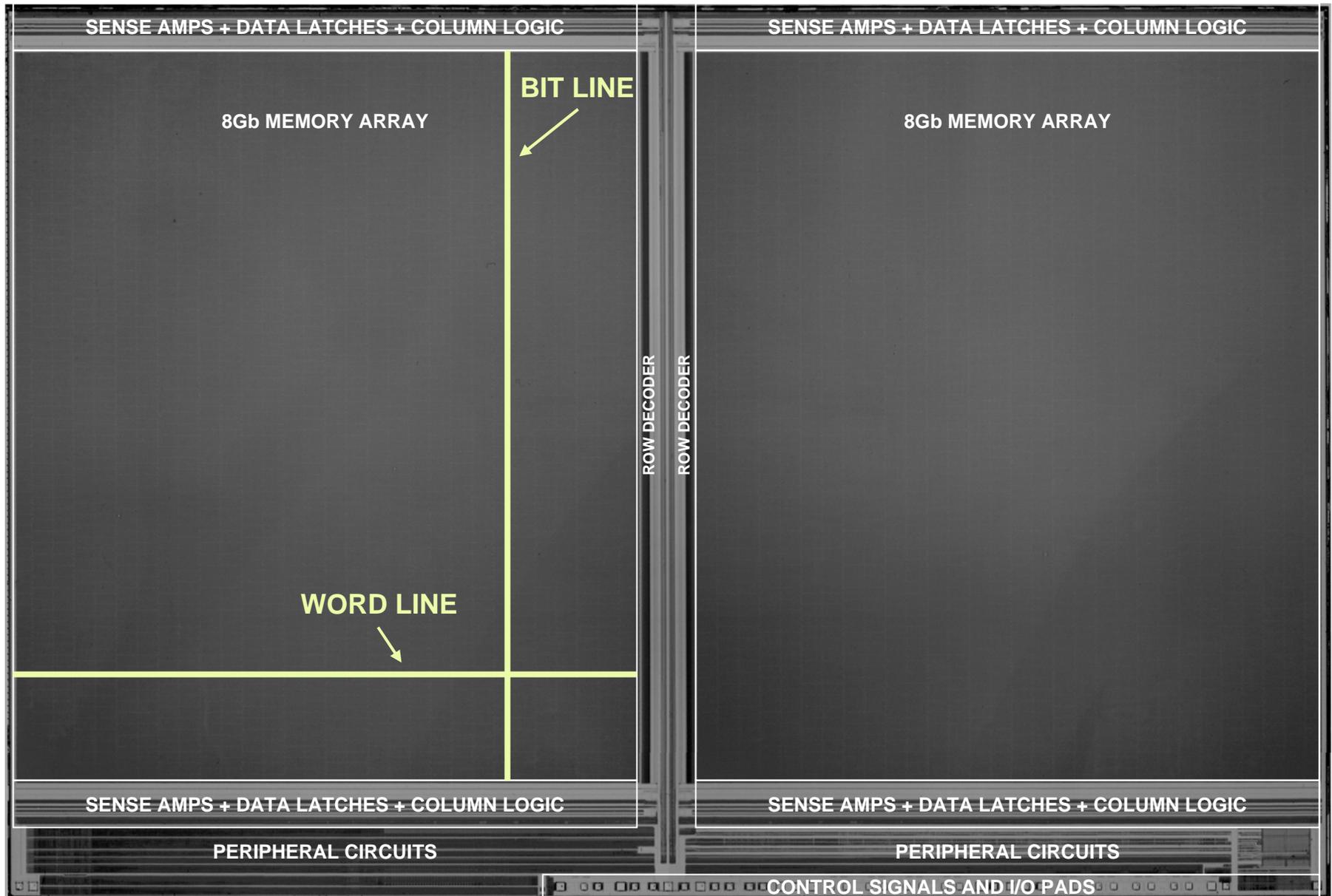
FOUR BITS PER CELL

Performance trends and All Bit Line Architecture

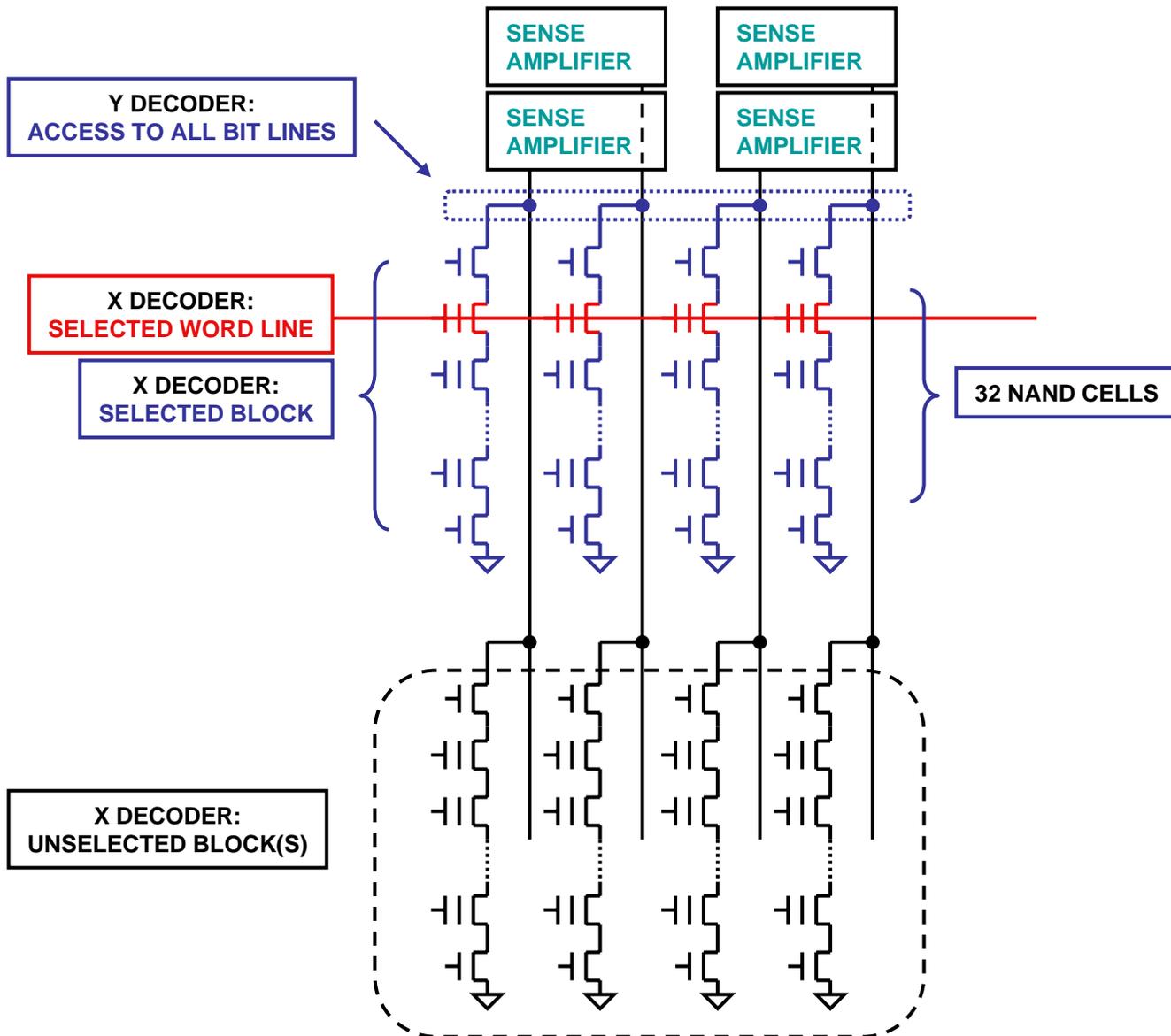
Program-throughput trends for NAND memories



The 16Gb chip

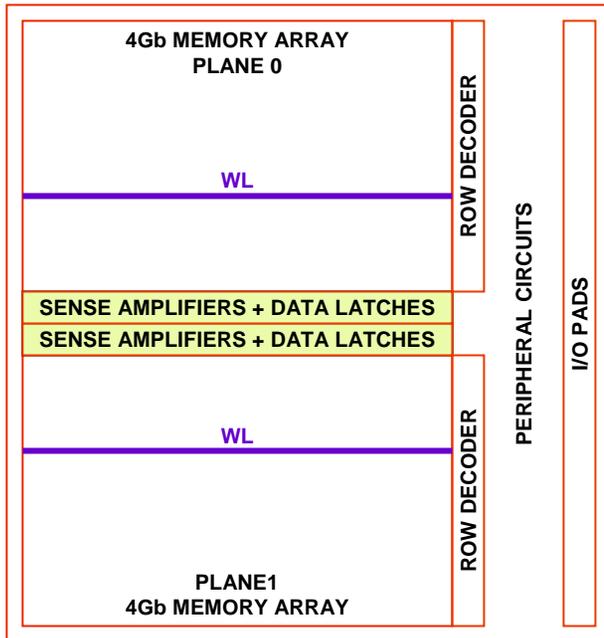


Cell access



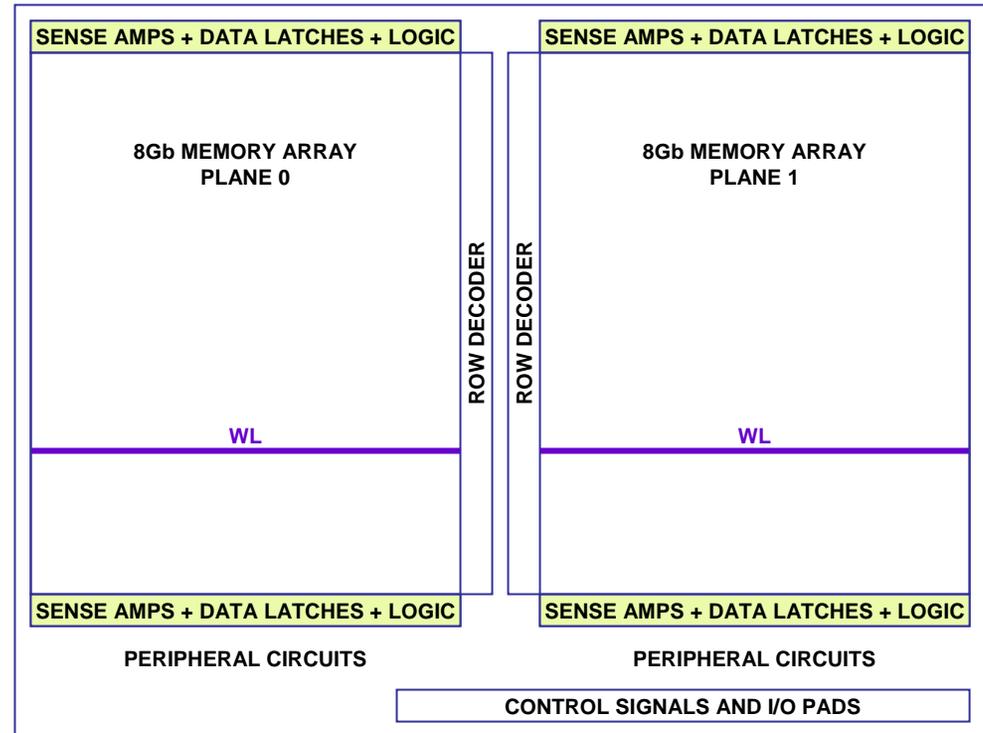
All Bit Line memory versus “Conventional”

8Gb CONVENTIONAL MEMORY



ISSCC 2006; 7.7

16Gb ABL MEMORY

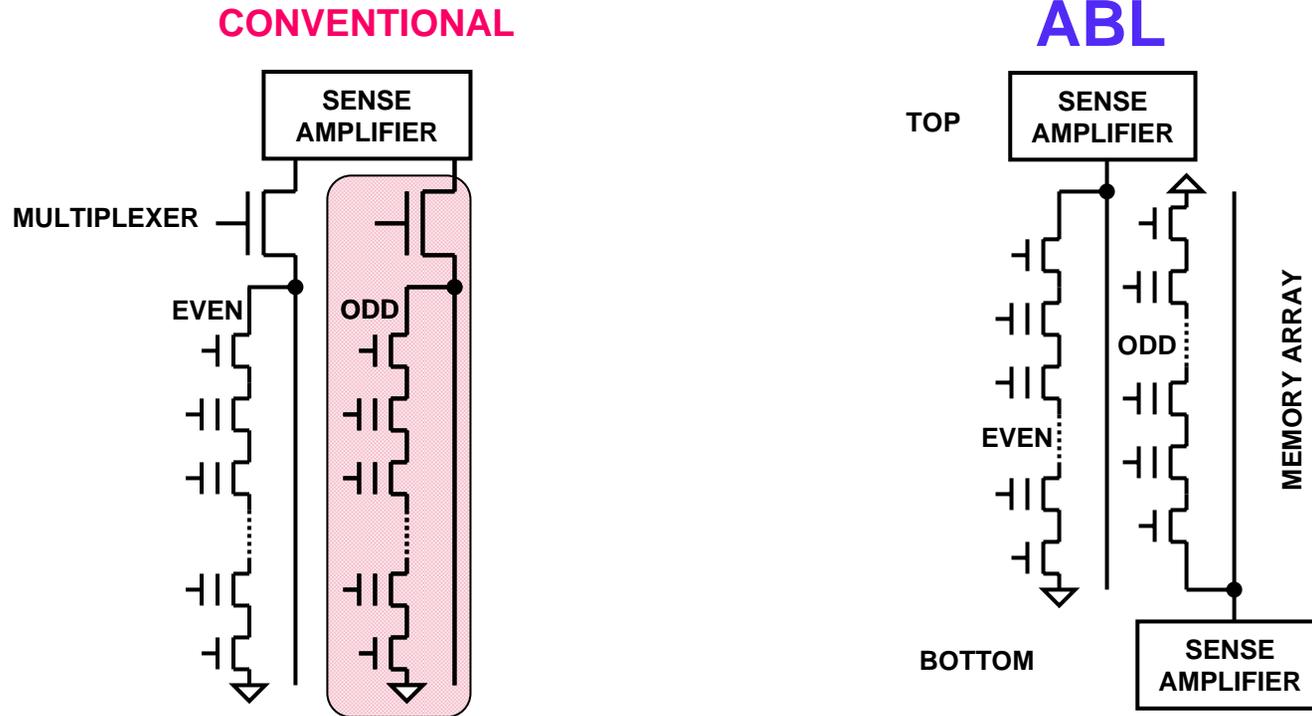


- Simultaneous access of two word lines of the same size
- ABL: double Column Logic, two sided

Differences between the two architectures

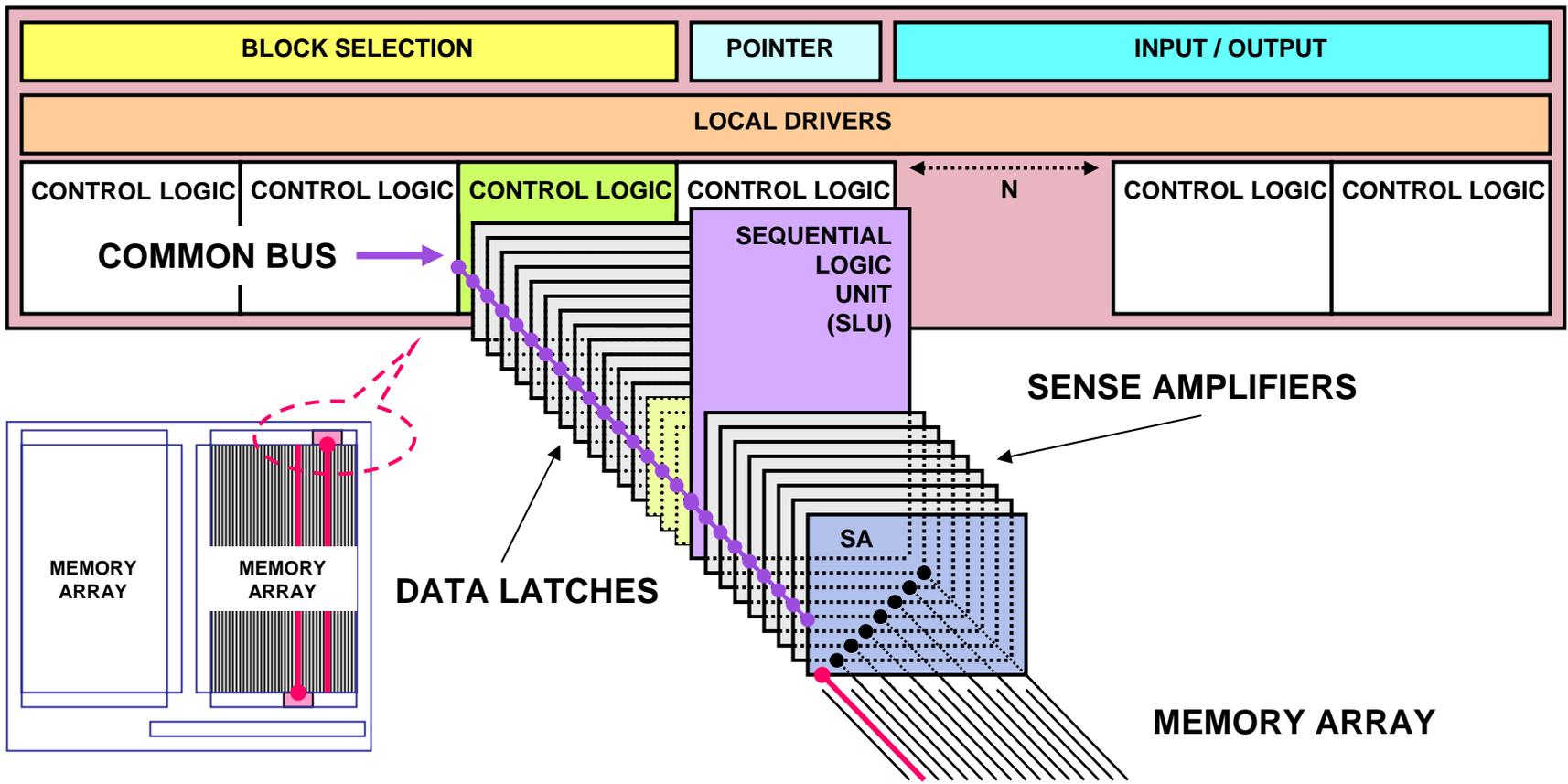
Features	Conventional	All Bit Line Full-Sequence
Density	8Gb	16Gb
Number of Blocks per Plane	1K	2K
Column Logic	One Sided	Two Sided
Number of Bit Lines per Sense Amplifier	2	1
4KB Pages Programmed in Parallel	2	8
Maximum MLC Program-Throughput	10MB/s	34MB/s

Maximum parallelism



- Conventional is an Even / Odd architecture
 - One Sense Amplifier handling two Bit Lines
 - Every other Bit Line shielded during sensing
- Full READ and PROGRAM capabilities for ABL
 - No shielding necessary (as in current mainstream NAND architecture)

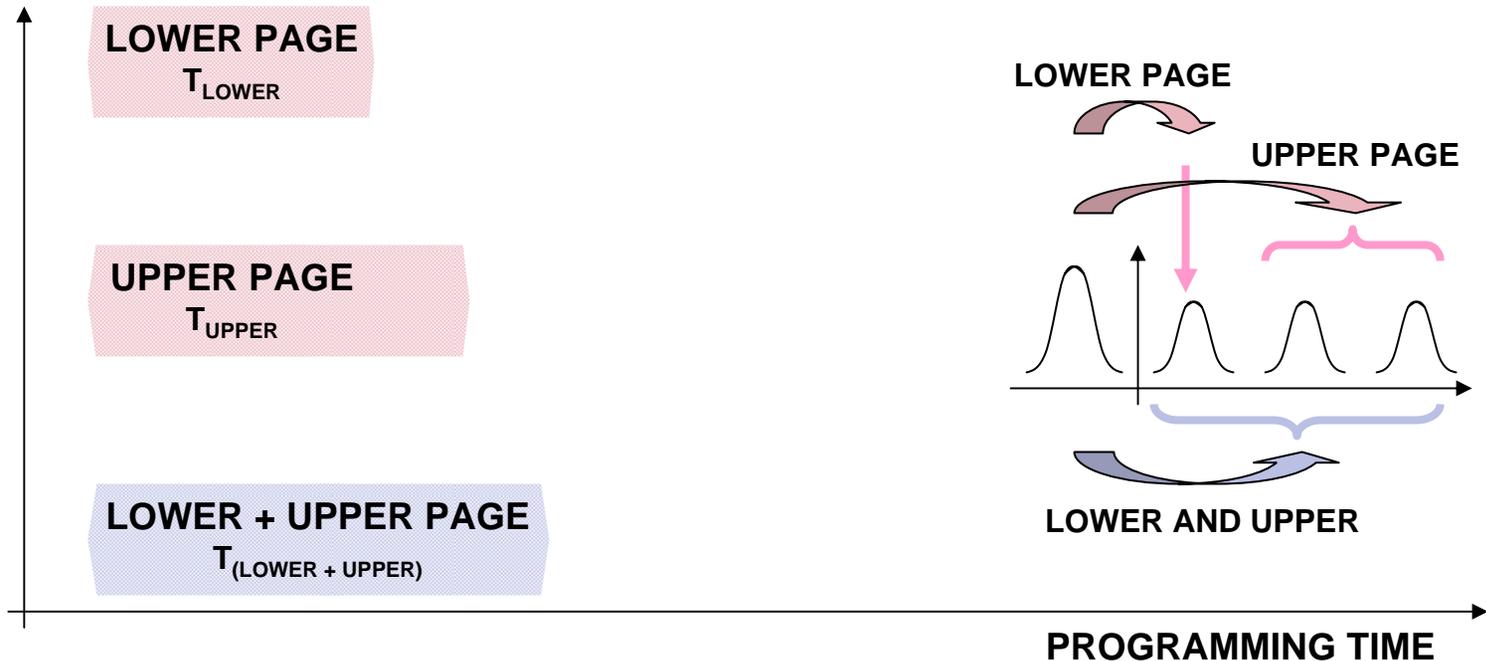
ABL: three level hierarchical architecture



- One Bit Line connected to one Sense Amplifier
- Sense Amplifiers, Data Latches, one Sequential Logic Unit and one Control Logic, all connected to the same bus
- Column Block Selection, Pointer, I/O and Local Drivers

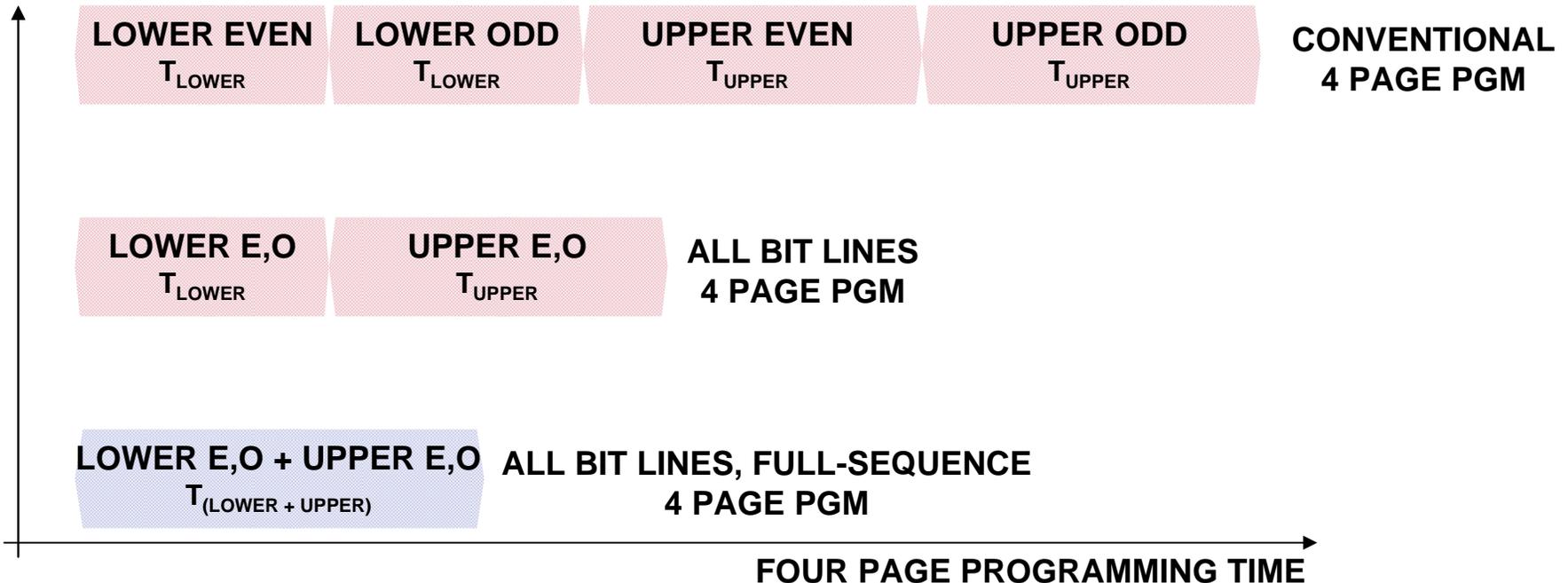
3X MLC Program-Throughput

MLC programming time



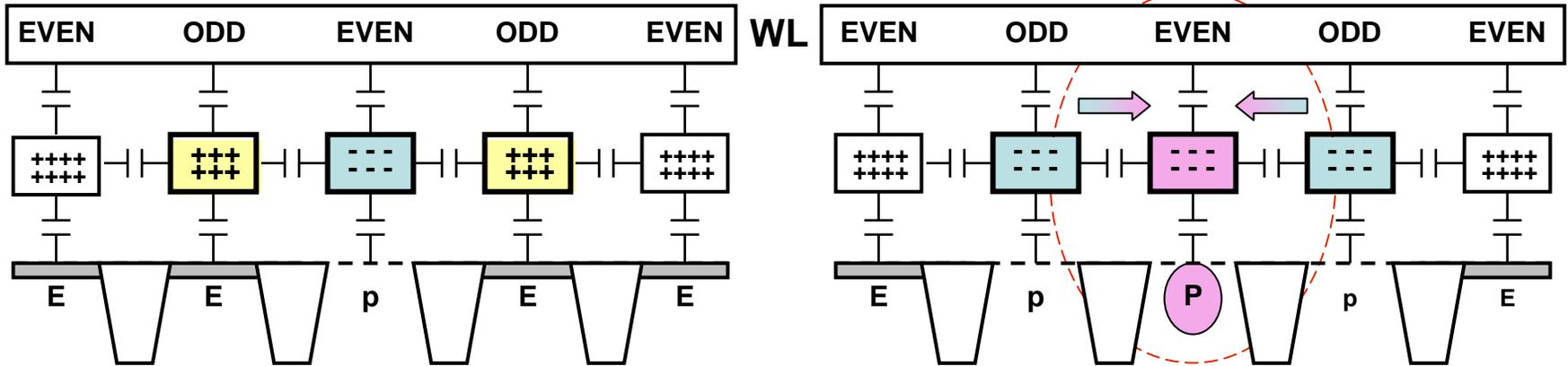
- There is a step up in programming time when one compares the lower page to the upper page (one state versus two states)
- The lower and upper pages together (three states) are the slowest to be programmed

Conventional, ABL and Full-Sequence



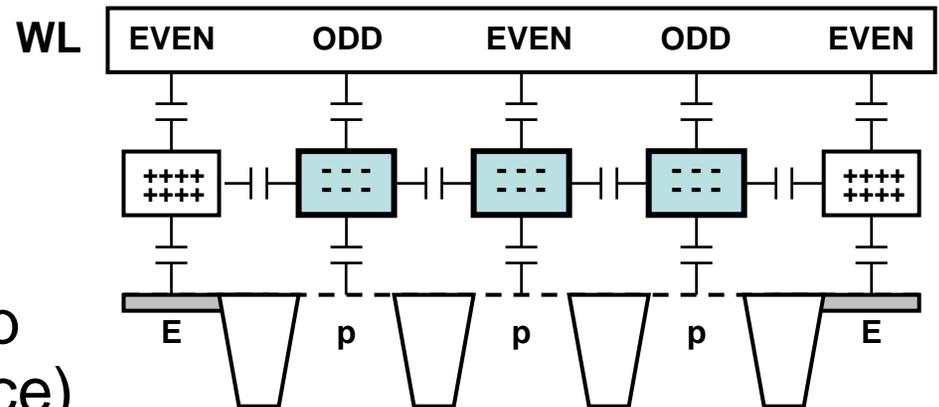
- In ABL architecture, programming four pages in parallel is twice as fast as Conventional
- MLC programming in Full-Sequence is about three times faster than Conventional

Yupin Effect



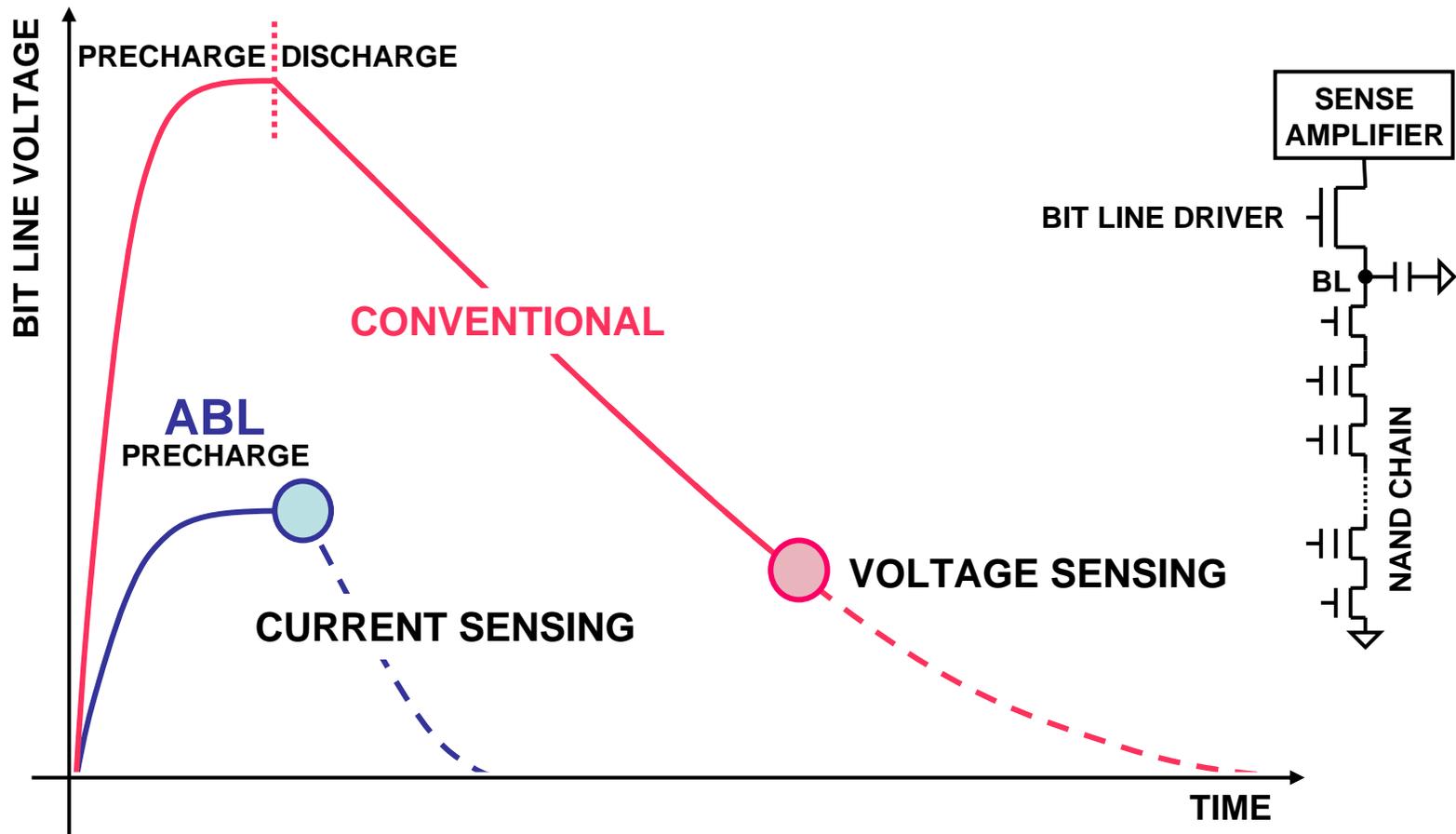
- Additional negative voltage in a two-step sequence for Floating Gates programmed in step TWO (Yupin Effect*)

Ref.: SanDisk US Patent 5,867,429 (Feb. 2 1999)



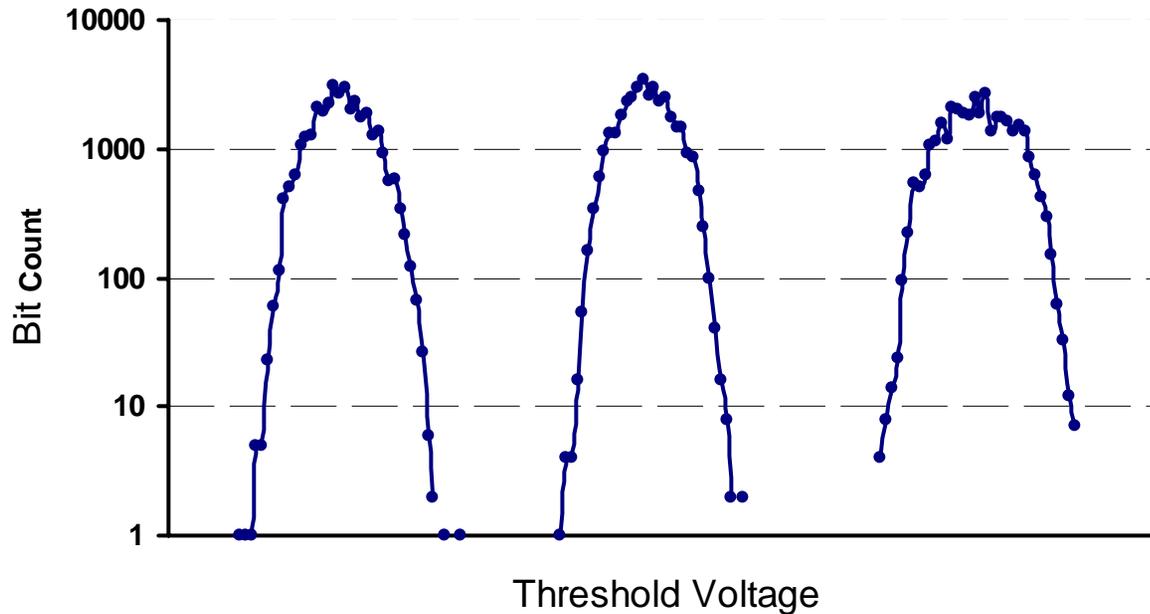
- Minimized effect in one-step programming (Full-Sequence)

ABL: faster verify with current sensing



- Pre-charge (by Bit Line driver): non-linear, fast (both)
- Discharge (by NAND cell): linear, slow (Conventional)
- Faster verify operation in ABL mode (pre-charge only)

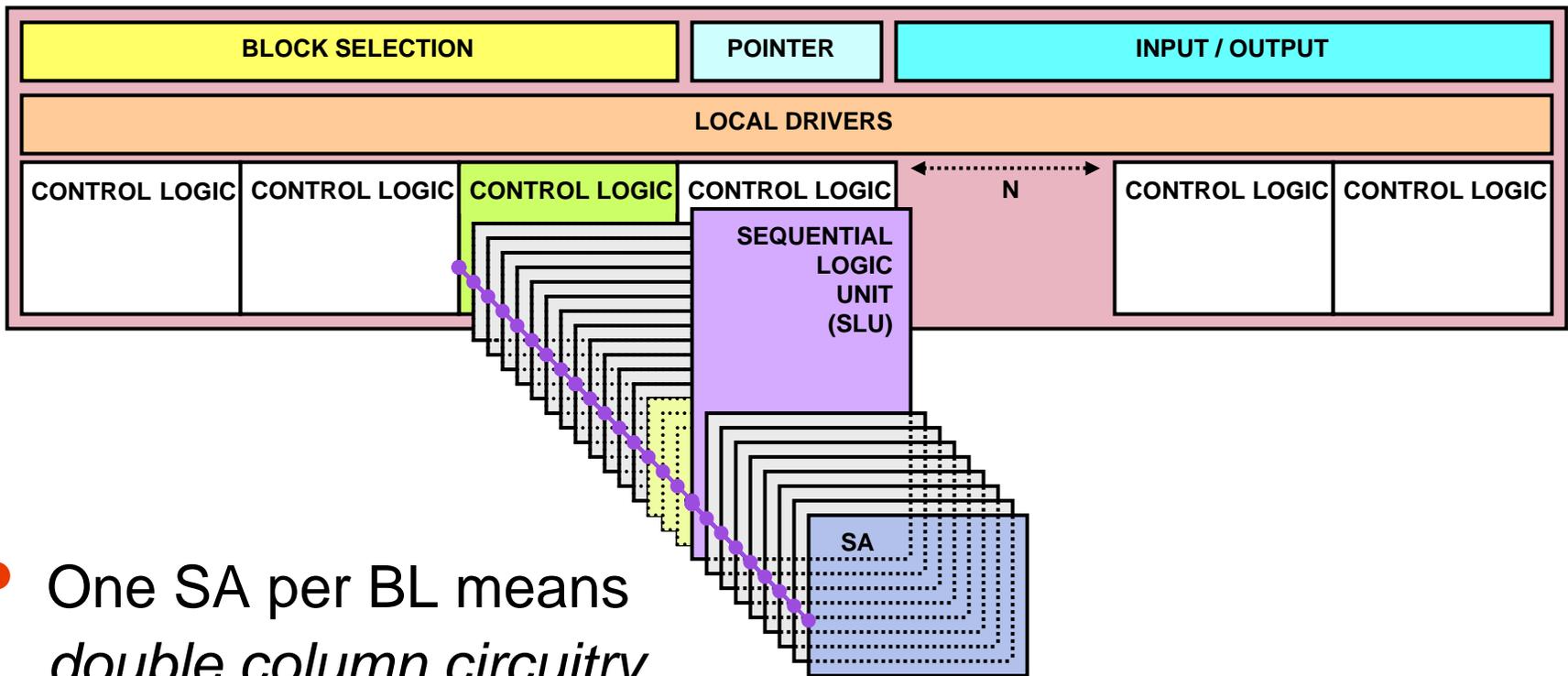
Random Data Distribution



- A full Word Line distribution of random data, programmed in ABL, Full-Sequence at a 34MB/s program-throughput

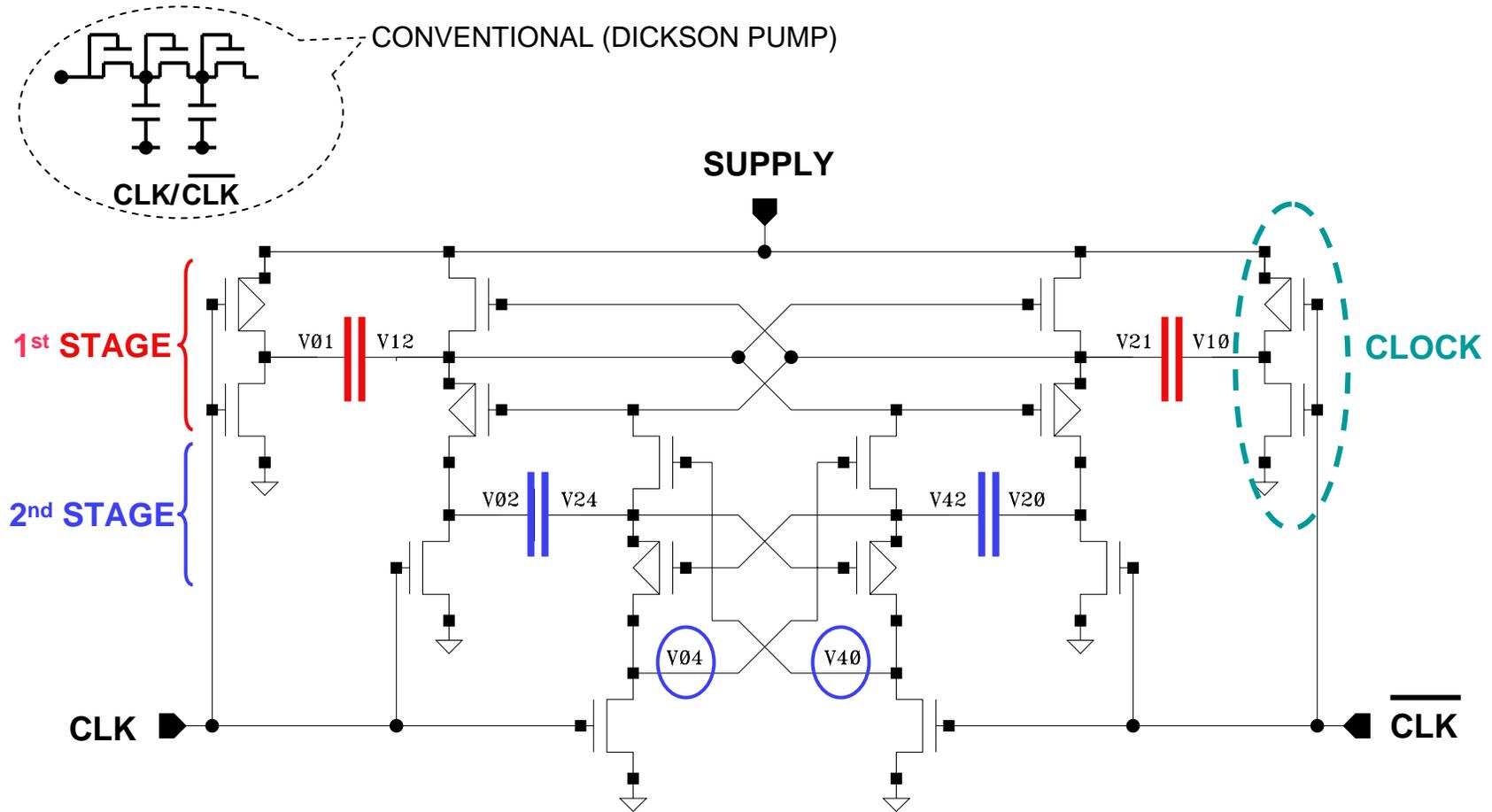
Die Size Challenge and Solutions

Hierarchical architecture for area saving



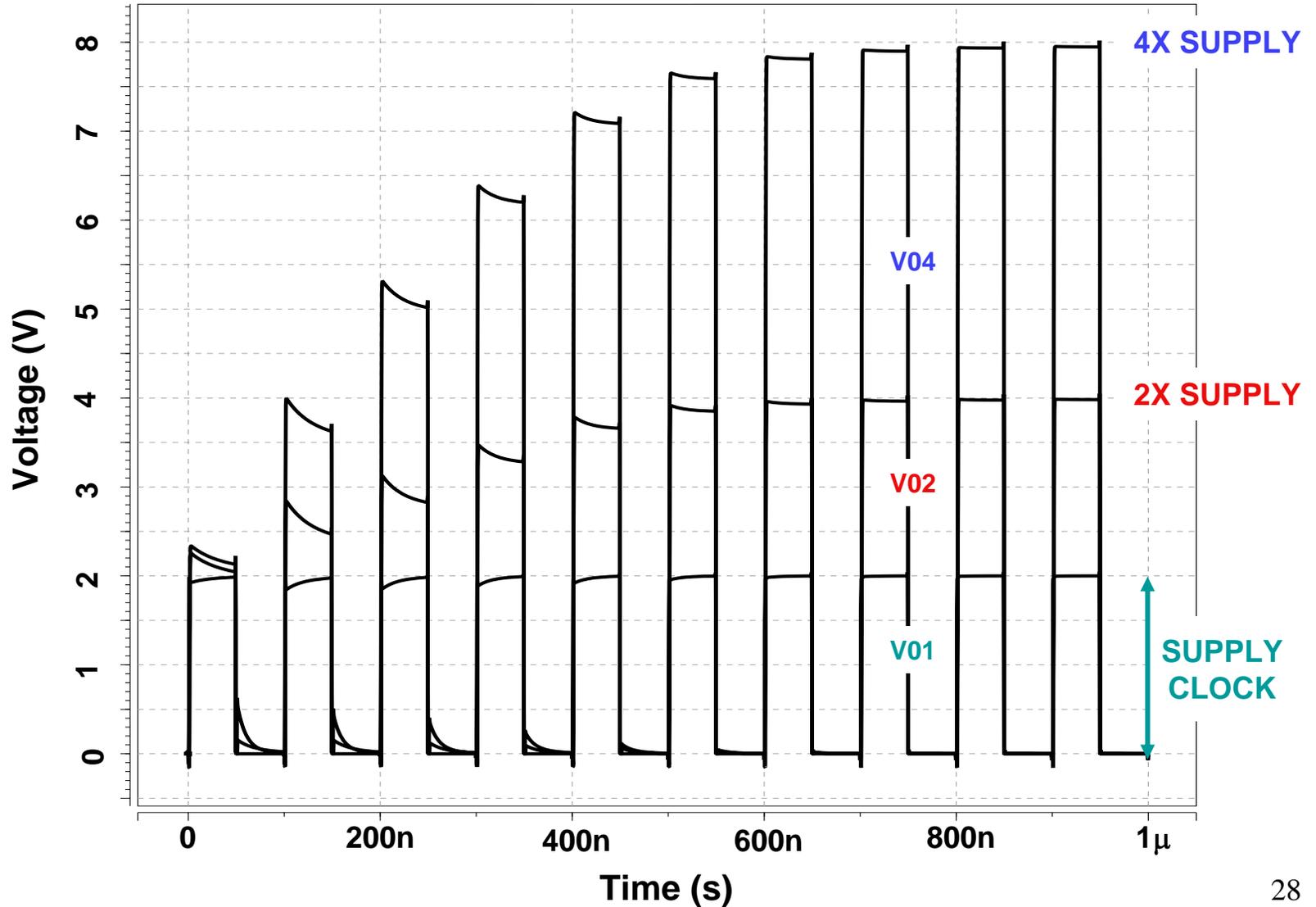
- One SA per BL means *double column circuitry*
 - Area reduction is a must
- Hierarchical architecture: less repeating circuits
 - Only one Sequential Logic Unit and Control Logic per group
 - Only one Block Selection, Pointer and I/O per block
- Saved area allows for local drivers

Efficient pumps for area saving



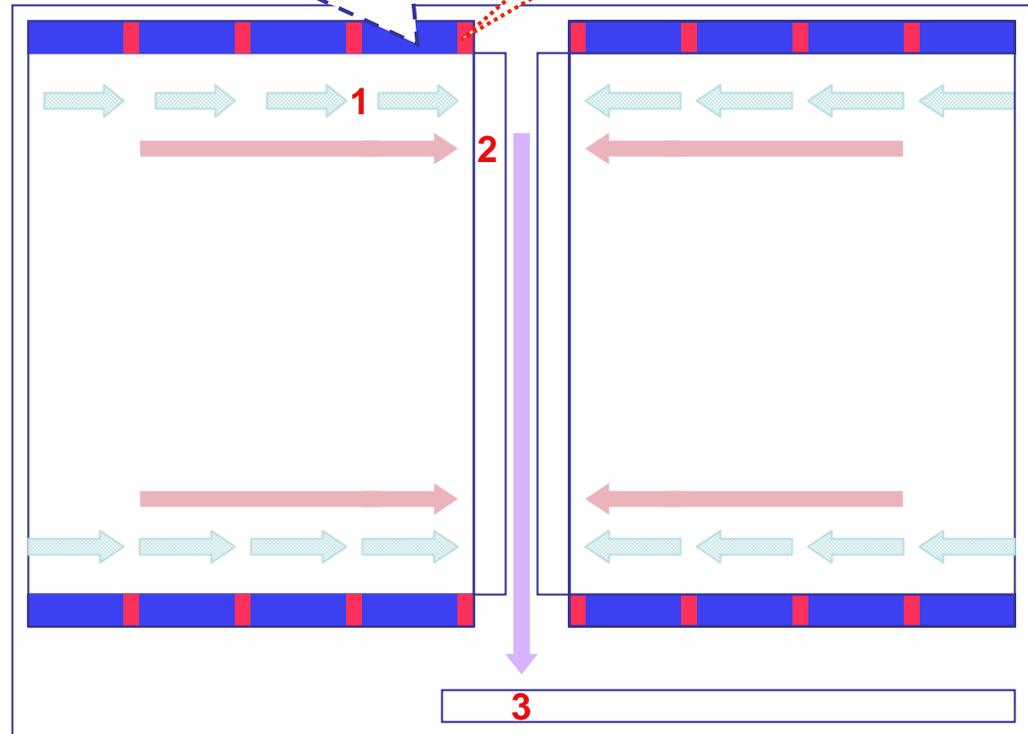
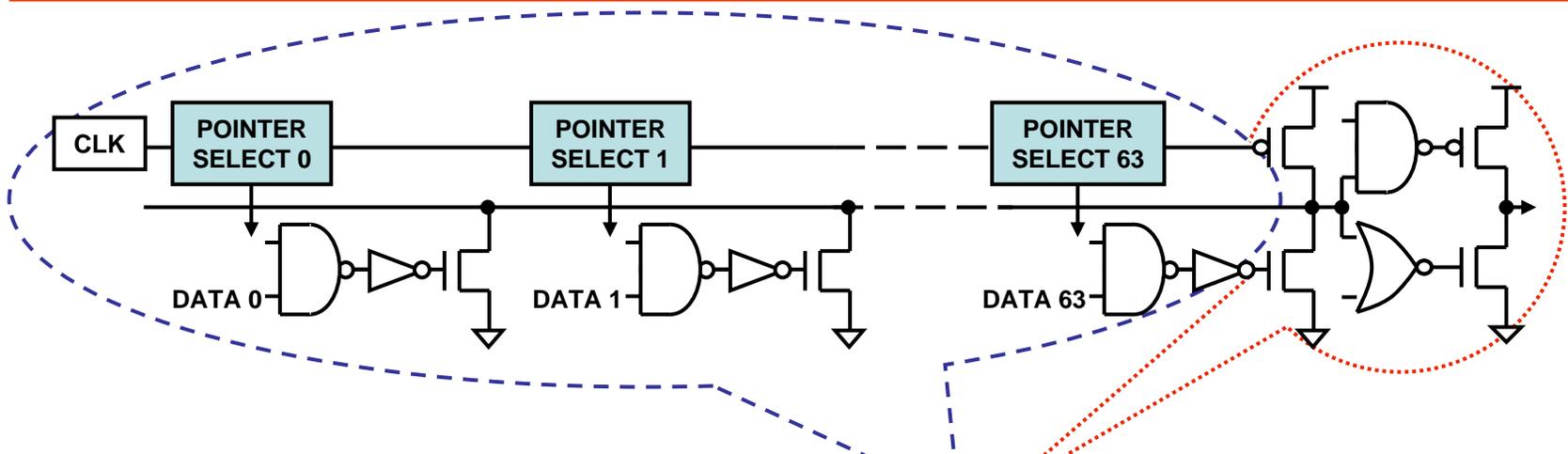
- Every stage doubles the (regulated) input voltage
- Cross coupled transistors as “Dynamical Diodes” to prevent the loss of one diode per stage

Each stage doubles the input voltage



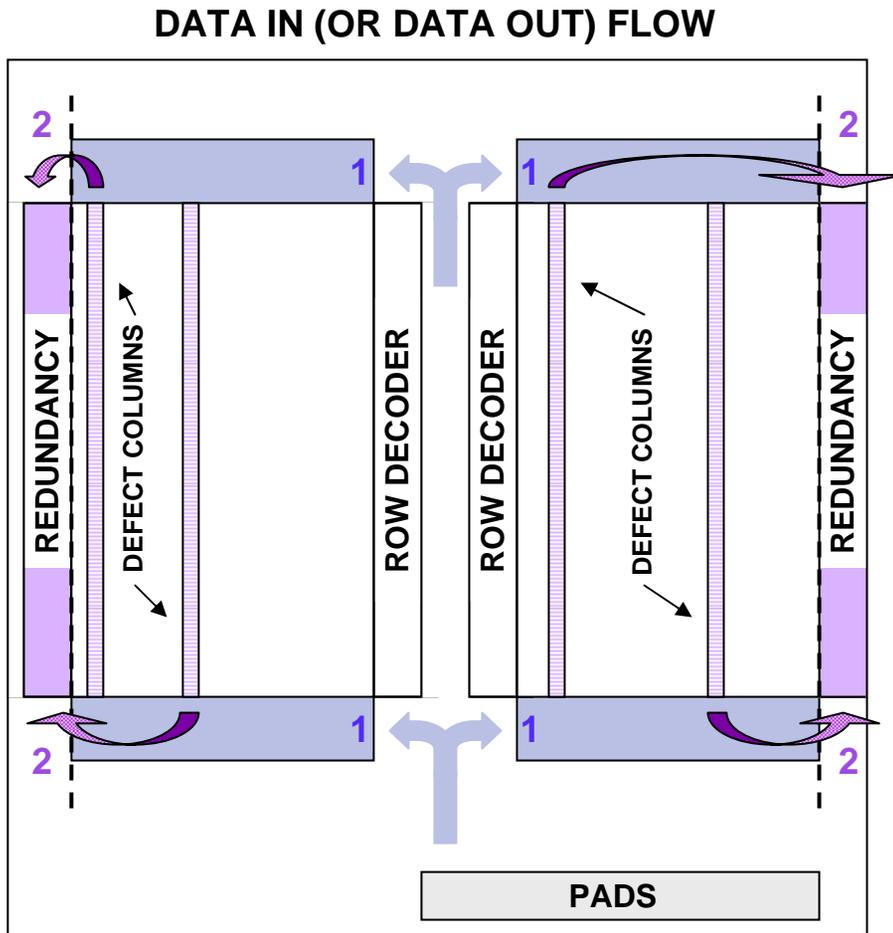
Accelerated Input / Output Access Rate

Fast internal data I/O stream



- Pointer selection
- Three stage pipeline
 1. Quad-split loading
 2. Four-point pick up
 3. Top / Bottom

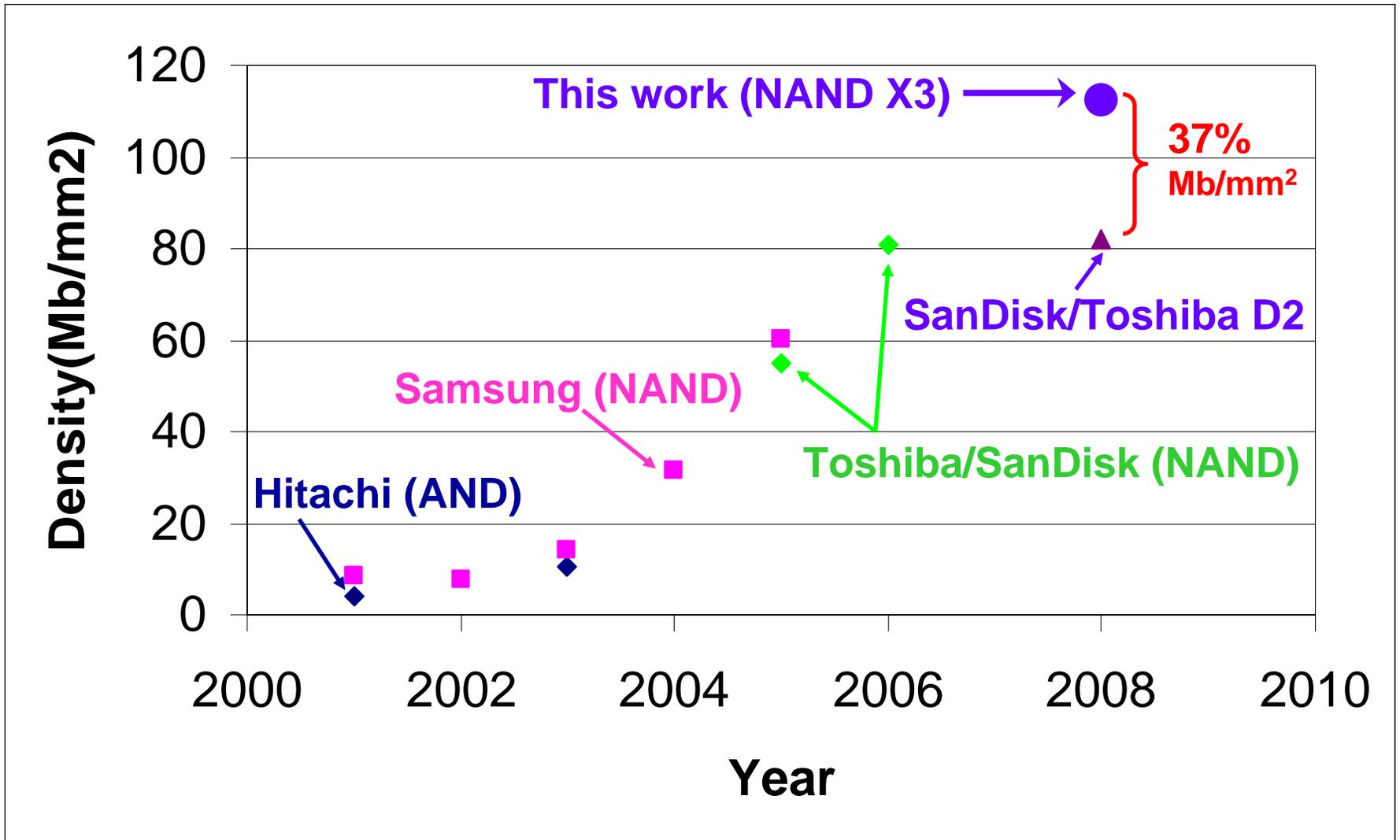
Two step I/O redundancy access



- Regular clock for redundancy bytes at Data In (or Data Out)
STEP 1: Full data stream into the regular buffer
STEP 2: Data transfer between regular buffer and redundancy zone
- Reversed process for Data Out
- Minimal time penalty for the hidden data transfer

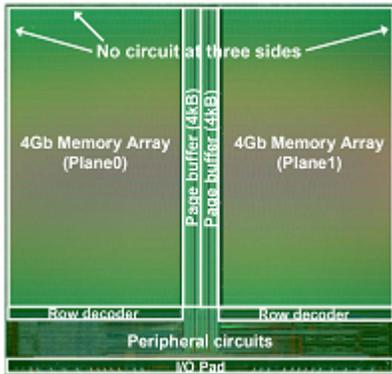
Three bits per cell

Memory Density Trend

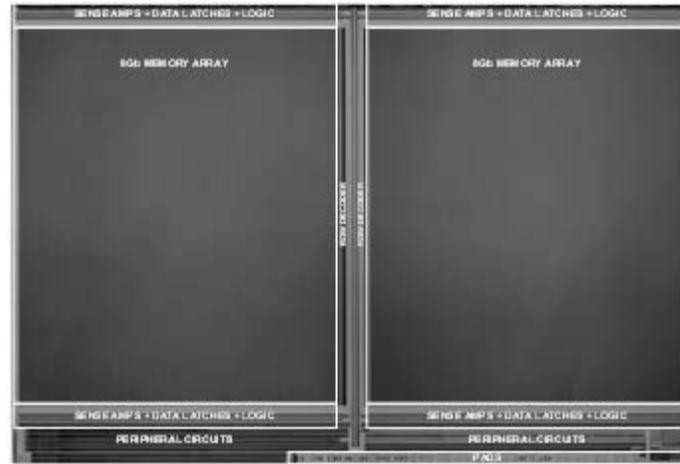


Chip architecture comparison

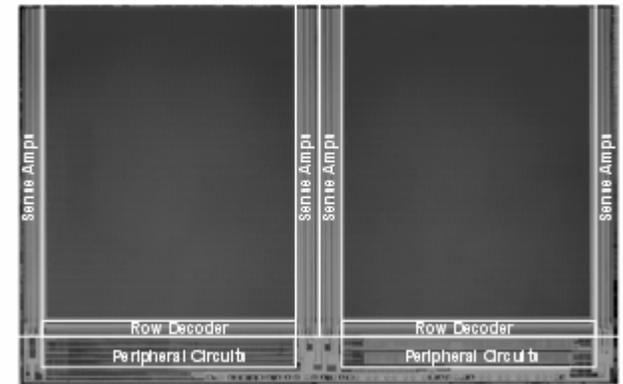
56nm 8G D2 (ISSCC2006)



56nm 16G D2 (ISSCC2008)

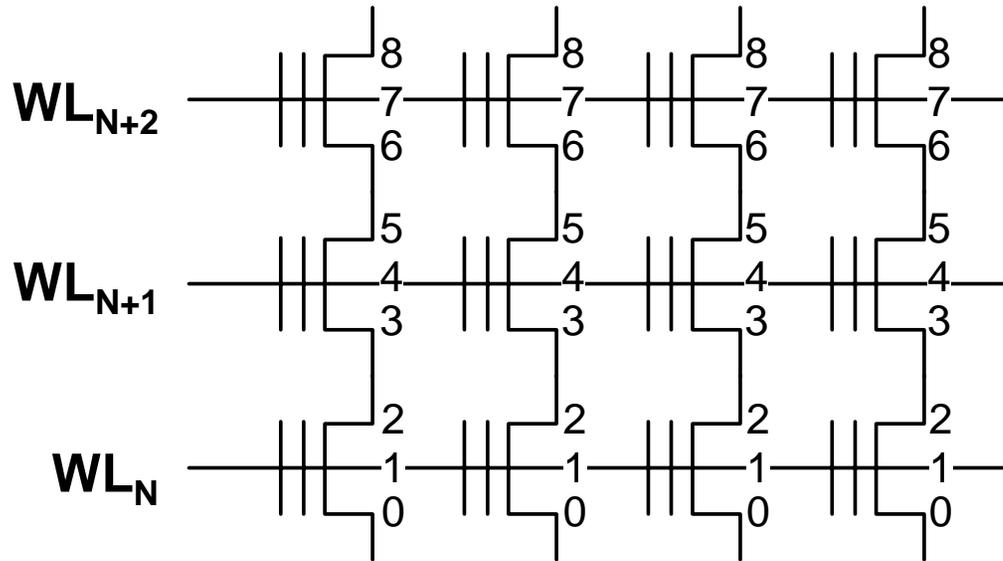


56nm 16G D3 (ISSCC2008) (This Work)



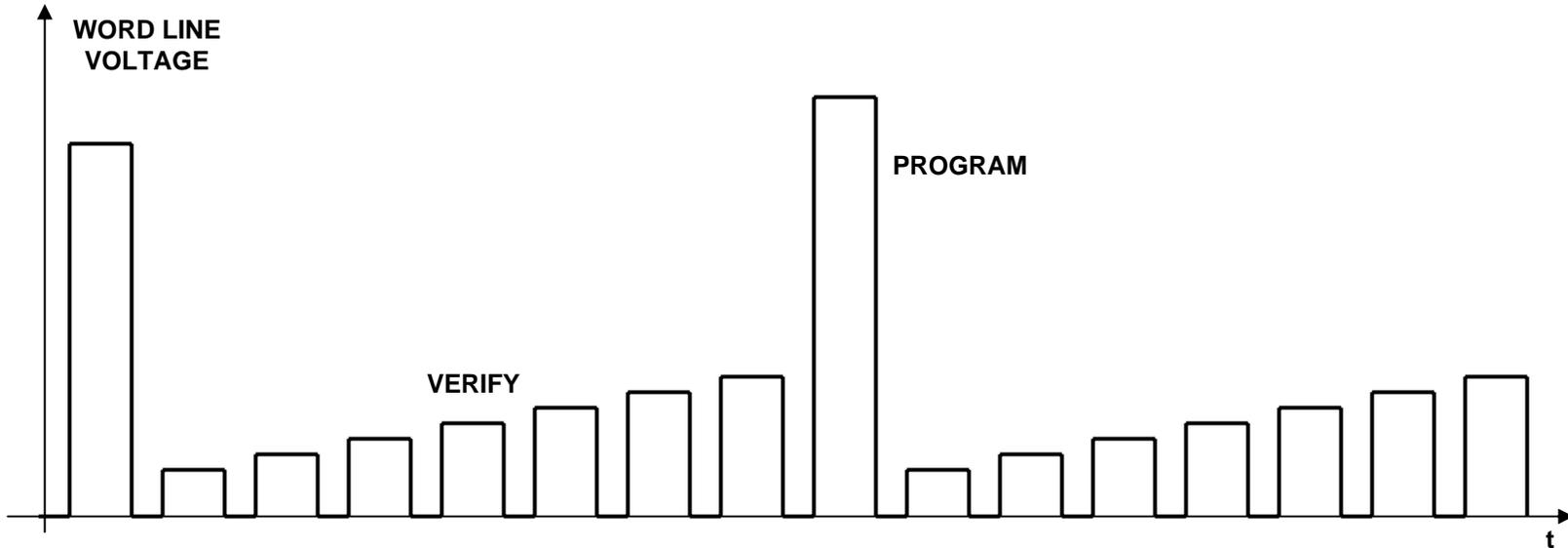
Chip size	99mm² ISSCC2006	182mm² ISSCC2008	142.5mm² (this work) (22% saving)
Density	8Gb (80.8Mb/mm ²)	16Gb (82Mb/mm ²) ↔	16Gb (112Mb/mm ²)
Architecture	4Gb / plane	8Gb / plane	8Gb / plane
Bits/Cell	2bits/cell	2bits/cell	3bits/cell
Program/Sense	Even or Odd	ABL	ABL

3 bit per cell programming



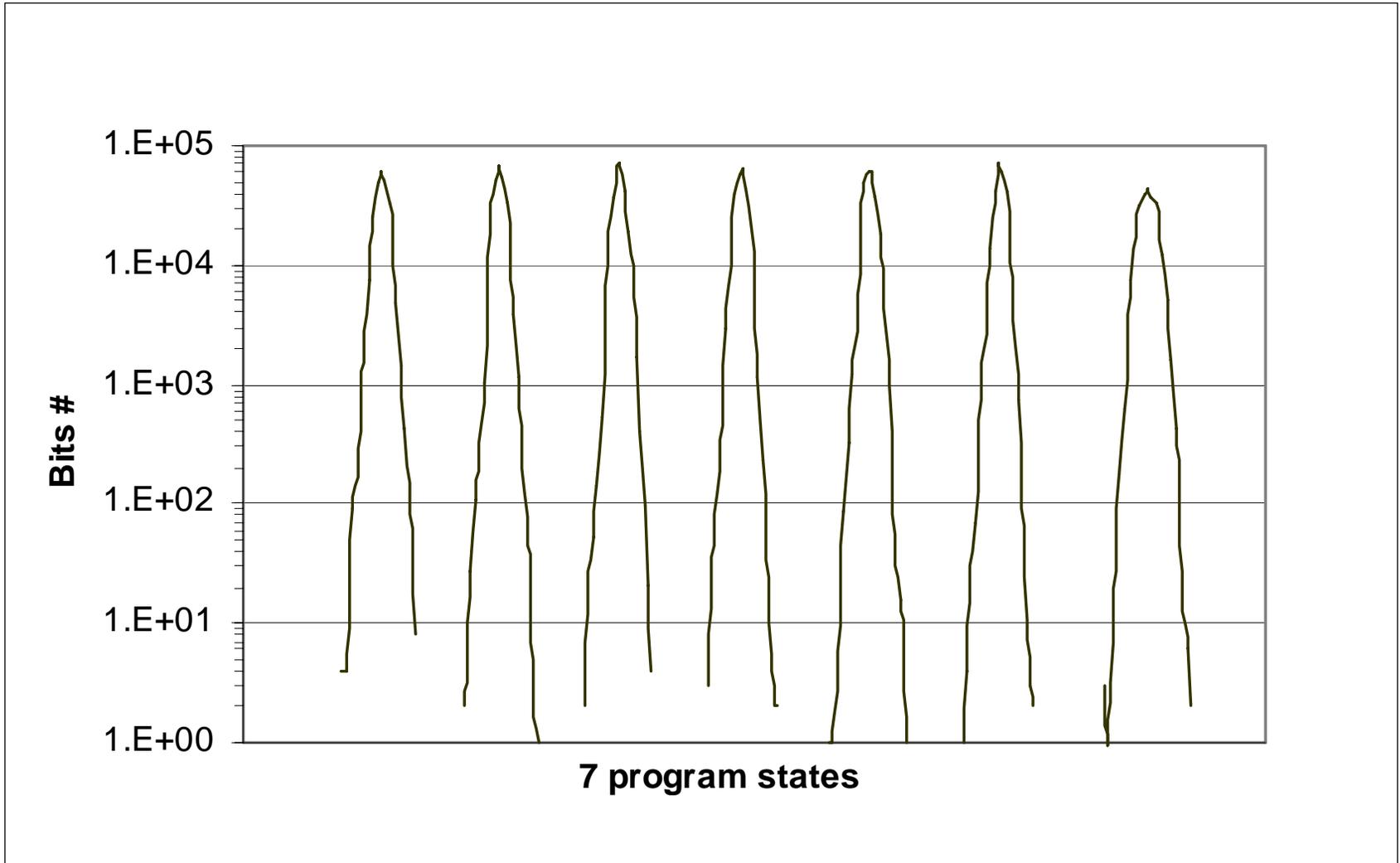
- 3 pages (Lower/Middle/Upper) on each Word Line
- Each page can be treated as an independent page
- The pages have to be programmed sequentially

3 bit per cell programming and verify



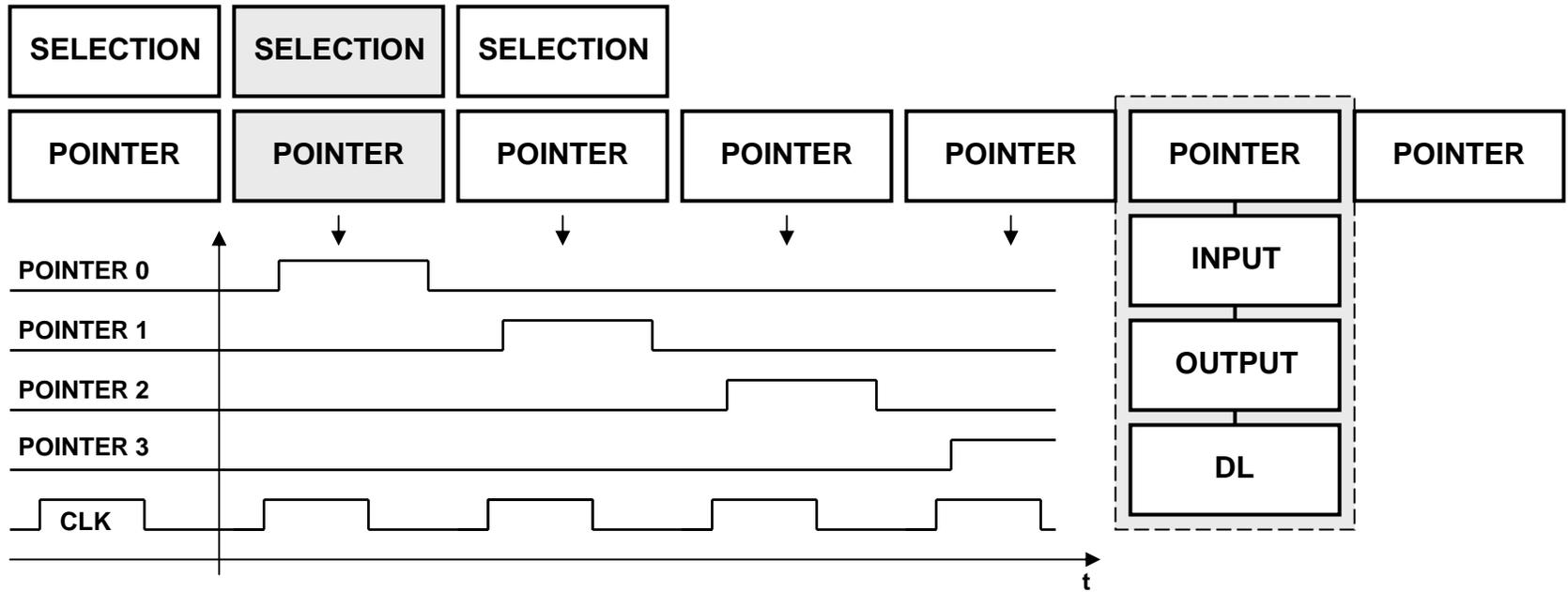
- 7 verify operations after each programming pulse
- Conversion from “page by page” to three page programming for speed improvement
- Program-throughput comparable to conventional (non-ABL 2 bit per cell)

7 state distribution



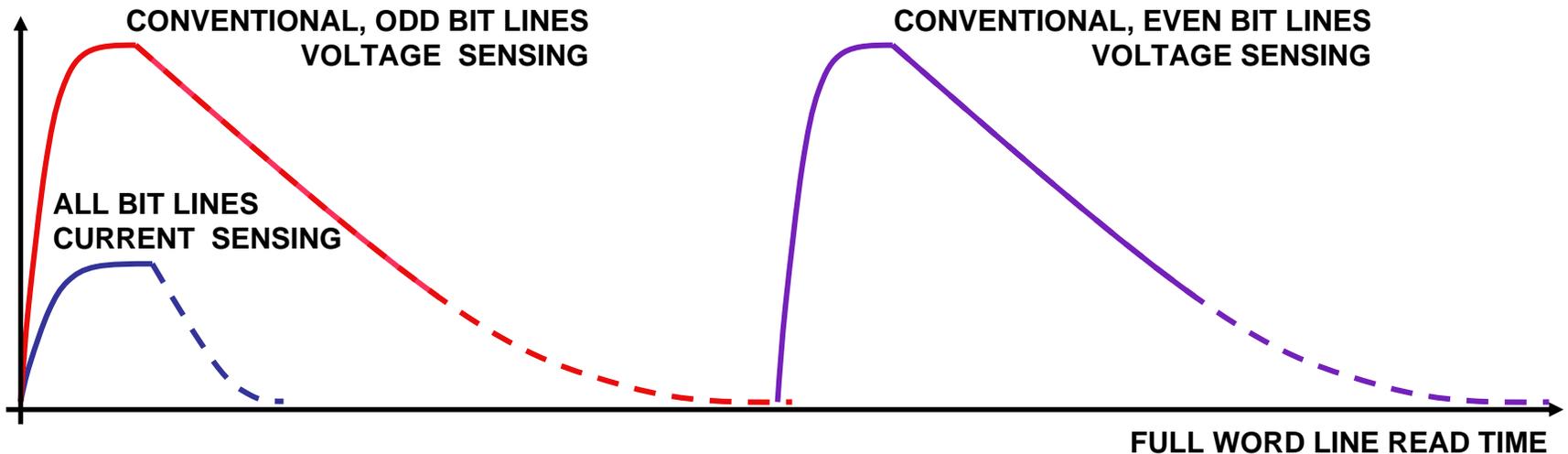
Power and Energy Reduction

Power reduction during Data Stream



- 2V internally down-regulated VDD (from 2.7~3.6V)
- Pointer selection to avoid global address bus switching

ABL for lower energy



- Even / Odd sensing in Conventional architecture
 - Double sensing operations per Word Line
 - Strong coupling between adjacent Bit Lines plus parasitic to Ground
- All Bit Line sensing in one operation
 - Bit Line coupling to ground only (20% of total parasitic)
 - Lower Bit Line voltages
- At least 10 times less charge wasted when using ABL

Summary and Conclusions

Summary, 2 bit per cell

READ THROUGHPUT BY 8 I/O	50MB/s
ABL SLC PROGRAMMING (WITHOUT HIGH SPEED I/O INTERFACE)	60MB/s
ABL MLC PROGRAMMING NO FULL-SEQUENCE	24MB/s
ABL MLC PROGRAMMING FULL-SEQUENCE	34MB/s
16 Gb ABL DIE SIZE	182mm²

Summary, 3 bit per cell

READ THROUGHPUT BY 8 I/O	40MB/s
ABL MLC PROGRAMMING FULL-SEQUENCE	8MB/s
16 Gb D3 DIE SIZE	142.5mm²

ABL is the architecture of the future

- The ABL architecture provides the fastest MLC program-throughput reported yet in 56nm and closes the gap between SLC and MLC
- By means of Full-Sequence programming the high voltage exposure is halved and the Bit Line interaction is minimized for maximum endurance
- The technology challenges of 43nm and beyond are well served by this architecture
- ABL is the architecture of choice for the next generations and 3 bit per cell encoding

Conclusions

- A new All Bit Line architecture boosts the MLC program-throughput of a 16Gb NAND by 240%
- With hierarchical column block architecture and a two-step redundancy access, a 50% faster internal I/O rate is achieved, even for lower power supply
- ABL provides an energy efficient system with an improved overall performance
- Lower die size when compared to a four plane “Conventional” chip of close performance

Acknowledgements

- The author wants to specially thank George Samachisa and Yan Li for their support
- The circuits presented here were made possible by the work of many engineers from SanDisk and ¹⁾Toshiba:

Long Pham, Farookh Moogat, Siu Chan, Binh Le, Shouchang Tsao, Tai-Yuan Tseng, Khanh Nguyen, Jason Li, Jayson Hu, Cynthia Hsu, Fanglin Zhang, Teruhiko Kamei, Hiroaki Nasu, Phil Kliza, Khin Htoo, Jeffrey Lutze, Yingda Dong, Masaaki Higashitani, Junnhui Yang, Hung-Szu Lin, Vamshi Sakhamuri, Jong Hak Yuh, Alan Li, Feng Pan, Sridhar Yadala, Subodh Taigor, Kishan Pradhan, James Lan, James Chan, Takumi Abe¹, Yasuyuki Fukuda¹, Hideo Mukai¹, Koichi Kawakami¹, Connie Liang, Tommy Ip, Shu-Fen Chang, Jaggi Lakshmipathi, Sharon Huynh, Dimitris Pantelakis, Seungpil Lee, Yupin Fong, Tien-Chien Kuo, Jong Park, Tapan Samaddar, Hao Nguyen, Man Mui, Emilio Yero, Gyuwan Kwon, Jun Wan, Tetsuya Kaneko¹, Hiroshi Maejima¹, Hitoshi Shiga¹, Makoto Hamada¹, Norihiro Fujita¹, Kazunori Kanebako¹, Eugene Tam, Anne Koh, Iris Lu, Calvin Kuo, Trung Pham, Jonathan Huynh, Qui Nguyen, Hardwell Chibvongodze, Mitsuyuki Watanabe, Ken Oowada, Grishma Shah, Byungki Woo, Ray Gao, Patrick Hong, Liping Peng, Debi Das, Dhritiman Ghosh, Vivek Kalluru, Sanjay Kulkarni, Mehrdad Mofidi, Khandker Quader, Chi-Ming Wang